74LVC109

Dual $\overline{JK}$ flip-flop with set and reset; positive-edge trigger

Rev. 5 — 29 November 2012 Product data sheet

1. General description

The 74LVC109A is a dual positive edge triggered $\overline{JK}$ flip-flop featuring:

- individual J and $\overline{K}$ inputs
- clock (CP) inputs
- set ($\overline{SD}$) and reset ($\overline{RD}$) inputs
- complementary Q and $\overline{Q}$ outputs

The set and reset are asynchronous active LOW inputs and operate independently of the clock input.

The J and $\overline{K}$ inputs control the state changes of the flip-flops as described in the mode select function table. The J and $\overline{K}$ inputs must be stable one set-up time before the LOW-to-HIGH clock transition for predictable operation. The $\overline{JK}$ design allows operation as a D-type flip-flop by tying the J and $\overline{K}$ inputs together.

Schmitt trigger action in the clock input makes the circuit highly tolerant of slower clock rise and fall times.

2. Features and benefits

- 5 V tolerant inputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
  - JESD8-7A (1.65 V to 1.95 V)
  - JESD8-5A (2.3 V to 2.7 V)
  - JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-B exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Specified from −40 °C to +85 °C and −40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

All types are specified from −40 °C to +125 °C.

Type number	Package		
	Name	Description	Version
74LVC109D	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74LVC109DB	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74LVC109PW	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1

4. Functional diagram

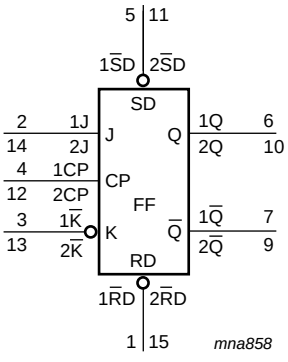


Fig 1. Logic symbol

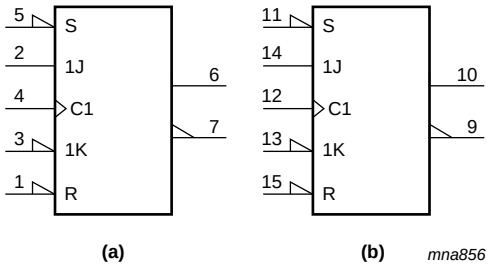


Fig 2. IEC logic symbol

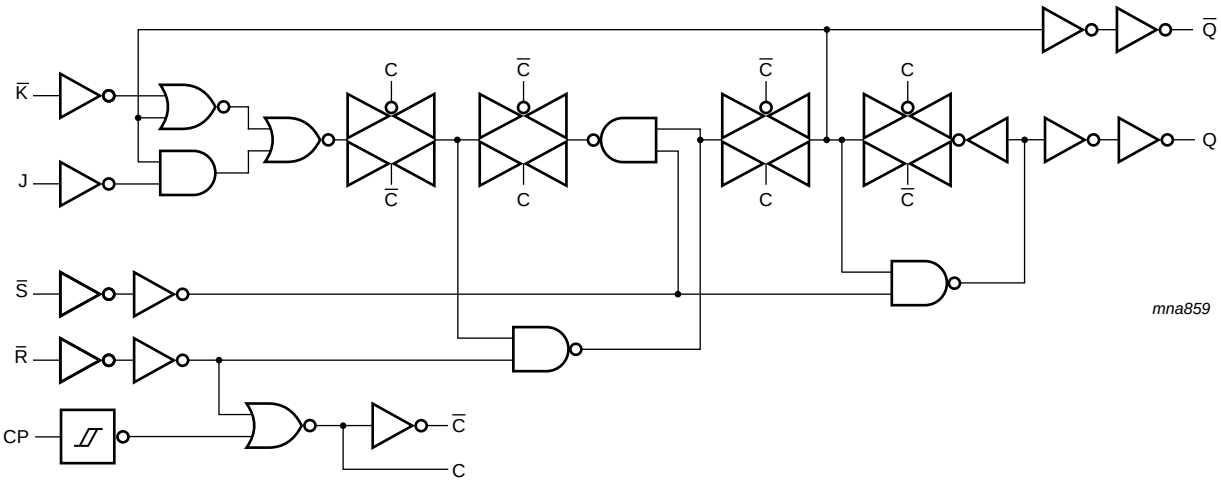


Fig 3. Logic diagram for one flip-flop

5. Pinning information

5.1 Pinning

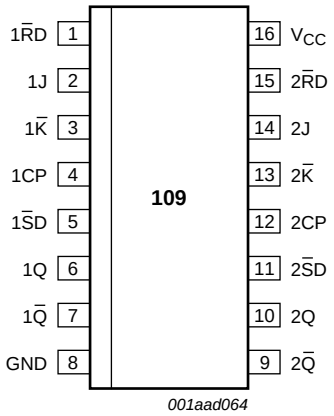


Fig 4. Pin configuration SO16 and (T)SSOP16

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1RD	1	asynchronous reset input (active LOW)
1J	2	synchronous input
1K	3	synchronous input
1CP	4	clock input (LOW-to-HIGH; edge-triggered)
1SD	5	asynchronous set input (active LOW)
1Q	6	true flip-flop output
1Q	7	complement flip-flop output
GND	8	ground (0 V)
2Q	9	complement flip-flop output
2Q	10	true flip-flop output
2SD	11	asynchronous set input (active LOW)
2CP	12	clock input (LOW-to-HIGH; edge-triggered)
2K	13	synchronous input
2J	14	synchronous input
2RD	15	asynchronous reset input (active LOW)
V_{CC}	16	supply voltage

6. Functional description

Table 3. Function selection[1]

Operating modes	Input					Output	
	$n\overline{SD}$	$n\overline{RD}$	nCP	nJ	$n\overline{K}$	nQ	$n\overline{Q}$
Asynchronous set	L	H	X	X	X	H	L
Asynchronous reset	H	L	X	X	X	L	H
Undetermined	L	L	X	X	X	H	H
Toggle	H	H	↑	h	l	$\overline{q}$	q
Load 0 (reset)	H	H	↑	l	l	L	H
Load 1 (set)	H	H	↑	h	h	H	L
Hold no change	H	H	↑	l	h	q	$\overline{q}$

[1] H = HIGH voltage level
h = HIGH voltage level one set-up time before the LOW-to-HIGH CP transition
L = LOW voltage level
l = LOW voltage level one set-up time before the LOW-to-HIGH CP transition
q = lower case letters indicate the state of the referenced output one set-up time before the LOW-to-HIGH CP transition
X = don't care
↑ = LOW-to-HIGH CP transition

7. Limiting values

Table 4. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			−0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V		−50	-	mA
V_I	input voltage		[1]	−0.5	+6.5	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V		-	±50	mA
V_O	output voltage		[2]	−0.5	V_{CC} + 0.5	V
I_O	output current	V_O = 0 V to V_{CC}		-	±50	mA
I_{CC}	supply current			-	100	mA
I_{GND}	ground current			−100	-	mA
P_{tot}	total power dissipation	T_{amb} = −40 °C to +125 °C	[3]	-	500	mW
T_{stg}	storage temperature			−65	+150	°C

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO16 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
For (T)SSOP16 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature	in free air	−40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 1.65 V to 2.7 V	0	-	20	ns/V
		V_{CC} = 2.7 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
V_{IH}	HIGH-level input voltage	V_{CC} = 1.2 V	1.08	-	-	1.08	-	V
		V_{CC} = 1.65 V to 1.95 V	0.65 × V_{CC}	-	-	0.65 × V_{CC}	-	V
		V_{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V_{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 1.2 V	-	-	0.12	-	0.12	V
		V_{CC} = 1.65 V to 1.95 V	-	-	0.35 × V_{CC}	-	0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V_{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = −100 μA; V_{CC} = 1.65 V to 3.6 V	V_{CC} − 0.2	-	-	V_{CC} − 0.3	-	V
		I_O = −4 mA; V_{CC} = 1.65 V	1.2	-	-	1.05	-	V
		I_O = −8 mA; V_{CC} = 2.3 V	1.8	-	-	1.65	-	V
		I_O = −12 mA; V_{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I_O = −18 mA; V_{CC} = 3.0 V	2.4	-	-	2.25	-	V
		I_O = −24 mA; V_{CC} = 3.0 V	2.2	-	-	2.0	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = 100 μA; V_{CC} = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I_O = 4 mA; V_{CC} = 1.65 V	-	-	0.45	-	0.65	V
		I_O = 8 mA; V_{CC} = 2.3 V	-	-	0.6	-	0.8	V
		I_O = 12 mA; V_{CC} = 2.7 V	-	-	0.4	-	0.6	V
		I_O = 24 mA; V_{CC} = 3.0 V	-	-	0.55	-	0.8	V
I_I	input leakage current	V_{CC} = 3.6 V; V_I = 5.5 V or GND	-	±0.1	±5	-	±20	μA

Table 6. Static characteristics *...continued*

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
I_{CC}	supply current	V_{CC} = 3.6 V; V_I = V_{CC} or GND; I_O = 0 A	-	0.1	10	-	40	µA
ΔI_{CC}	additional supply current	per input pin; V_{CC} = 2.7 V to 3.6 V; V_I = V_{CC} − 0.6 V; I_O = 0 A	-	5	500	-	5000	µA
C_I	input capacitance	V_{CC} = 0 V to 3.6 V; V_I = GND to V_{CC}	-	5.0	-	-	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 7.

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
t_{pd}	propagation delay	nCP to nQ, n$\overline{Q}$; see Figure 5 [2]						
		V_{CC} = 1.2 V	-	15	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V	1.7	6.8	15.0	1.7	17.4	ns
		V_{CC} = 2.3 V to 2.7 V	2.7	3.9	8.1	2.7	9.4	ns
		V_{CC} = 2.7 V	1.5	3.9	7.3	1.5	9.5	ns
		V_{CC} = 3.0 V to 3.6 V	1.0	3.5	6.8	1.0	8.5	ns
t_{PLH}	LOW to HIGH propagation delay	n$\overline{SD}$, n$\overline{RD}$ to nQ, n$\overline{Q}$; see Figure 6						
		V_{CC} = 1.2 V	-	16	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V	1.0	6.2	15.6	1.0	18.0	ns
		V_{CC} = 2.3 V to 2.7 V	1.5	3.6	8.3	1.5	9.7	ns
		V_{CC} = 2.7 V	1.5	4.5	8.2	1.5	10.5	ns
		V_{CC} = 3.0 V to 3.6 V	1.0	3.3	7.0	1.0	9.0	ns
t_{PHL}	HIGH to LOW propagation delay	n$\overline{SD}$, n$\overline{RD}$ to nQ, n$\overline{Q}$; see Figure 6						
		V_{CC} = 1.2 V	-	13	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V	1.5	6.7	14.4	1.5	16.7	ns
		V_{CC} = 2.3 V to 2.7 V	2.0	3.8	7.7	2.0	9.0	ns
		V_{CC} = 2.7 V	1.5	4.1	7.1	1.5	9.0	ns
		V_{CC} = 3.0 V to 3.6 V	1.0	3.5	6.5	1.0	8.5	ns

Table 7. Dynamic characteristics *...continued*

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 7.

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
t_W	pulse width	clock HIGH or LOW; see Figure 5						
		V_{CC} = 1.65 V to 1.95 V	5.0	-	-	5.0	-	ns
		V_{CC} = 2.3 V to 2.7 V	4.0	-	-	4.0	-	ns
		V_{CC} = 2.7 V	3.3	-	-	3.3	-	ns
		V_{CC} = 3.0 V to 3.6 V	3.3	2.0	-	3.3	-	ns
		set or reset HIGH or LOW; see Figure 6						
		V_{CC} = 1.65 V to 1.95 V	5.0	-	-	5.0	-	ns
		V_{CC} = 2.3 V to 2.7 V	4.0	-	-	4.0	-	ns
		V_{CC} = 2.7 V	3.0	-	-	3.0	-	ns
		V_{CC} = 3.0 V to 3.6 V	3.0	-	-	3.0	-	ns
t_{rec}	recovery time	$n\overline{SD}$, $n\overline{RD}$ to nCP; see Figure 6						
		V_{CC} = 1.65 V to 1.95 V	5.5	-	-	5.5	-	ns
		V_{CC} = 2.3 V to 2.7 V	4.0	-	-	4.0	-	ns
		V_{CC} = 2.7 V	3.2	-	-	3.2	-	ns
		V_{CC} = 3.0 V to 3.6 V	3.0	-	-	3.0	-	ns
t_{su}	set-up time	nJ and $n\overline{K}$ to CP; see Figure 5						
		V_{CC} = 1.65 V to 1.95 V	5.0	-	-	5.0	-	ns
		V_{CC} = 2.3 V to 2.7 V	3.5	-	-	3.5	-	ns
		V_{CC} = 2.7 V	2.7	-	-	2.7	-	ns
		V_{CC} = 3.0 V to 3.6 V	2.5	-	-	2.5	-	ns
t_h	hold time	nJ and $n\overline{K}$ to nCP; see Figure 5						
		V_{CC} = 1.65 V to 1.95 V	3.0	-	-	3.0	-	ns
		V_{CC} = 2.3 V to 2.7 V	2.5	-	-	2.5	-	ns
		V_{CC} = 2.7 V	2.2	-	-	2.2	-	ns
		V_{CC} = 3.0 V to 3.6 V	2.0	-	-	2.0	-	ns
f_{max}	maximum frequency	see Figure 5						
		V_{CC} = 1.65 V to 1.95 V	100	-	-	80	-	MHz
		V_{CC} = 2.3 V to 2.7 V	125	-	-	100	-	MHz
		V_{CC} = 2.7 V	150	-	-	120	-	MHz
		V_{CC} = 3.0 V to 3.6 V	150	330	-	120	-	MHz
$t_{sk(o)}$	output skew time	V_{CC} = 3.0 V to 3.6 V [3]	-	-	1.0	-	1.5	ns
C_{PD}	power dissipation capacitance	V_I = GND to V_{CC} [4]						
		V_{CC} = 1.65 V to 1.95 V	-	11.4	-	-	-	pF
		V_{CC} = 2.3 V to 2.7 V	-	17.6	-	-	-	pF
		V_{CC} = 3.0 V to 3.6 V	-	23.1	-	-	-	pF

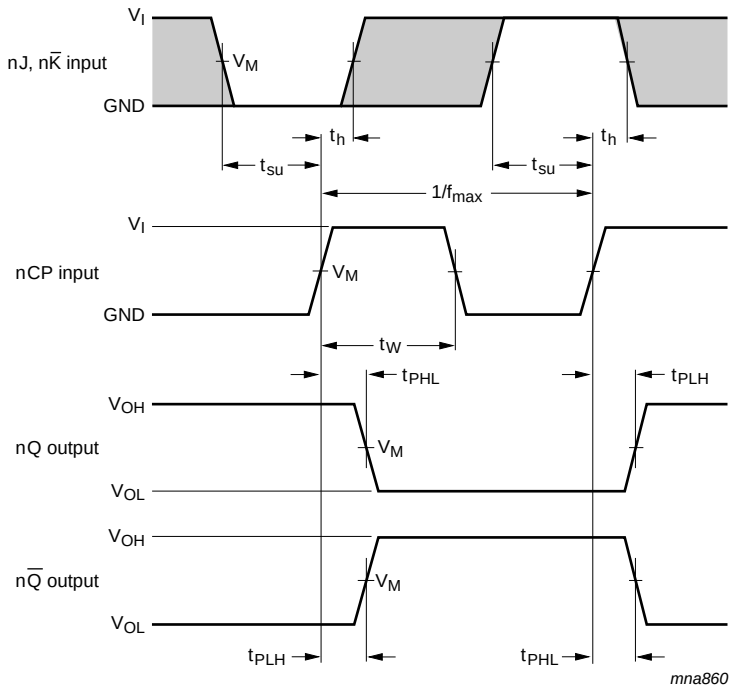
[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz; f_o = output frequency in MHz
C_L = output load capacitance in pF
V_{CC} = supply voltage in Volts
N = number of inputs switching
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs

11. AC waveforms

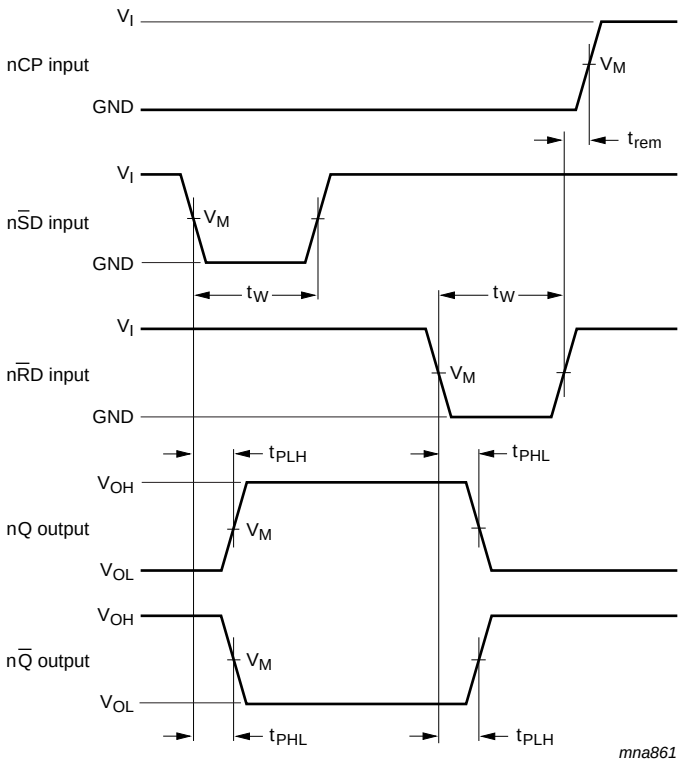


Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

The shaded areas indicate when the input is permitted to change for predictable output performance.

Fig 5. Clock propagation delays, pulse width, set-up, hold times, and maximum frequency



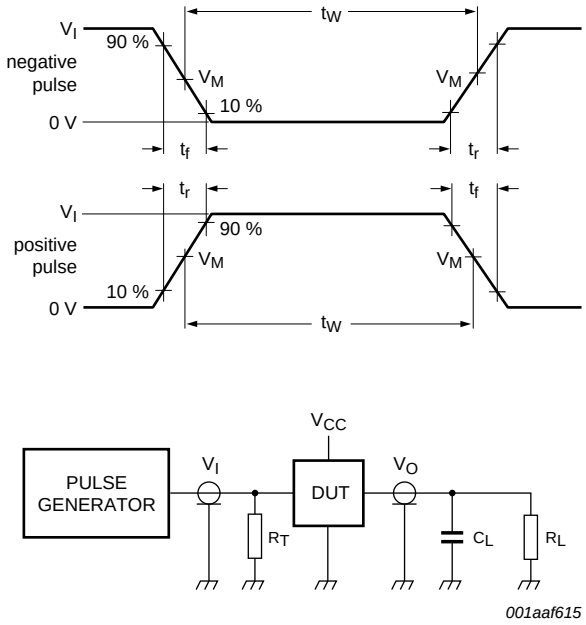
Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. Set and reset propagation delays, pulse widths and recovery times

Table 8. Measurement points

Supply voltage	Input		Output
V_{CC}	V_I	V_M	V_M
1.2 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
1.65 V to 1.95 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V



Test data is given in Table 9.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

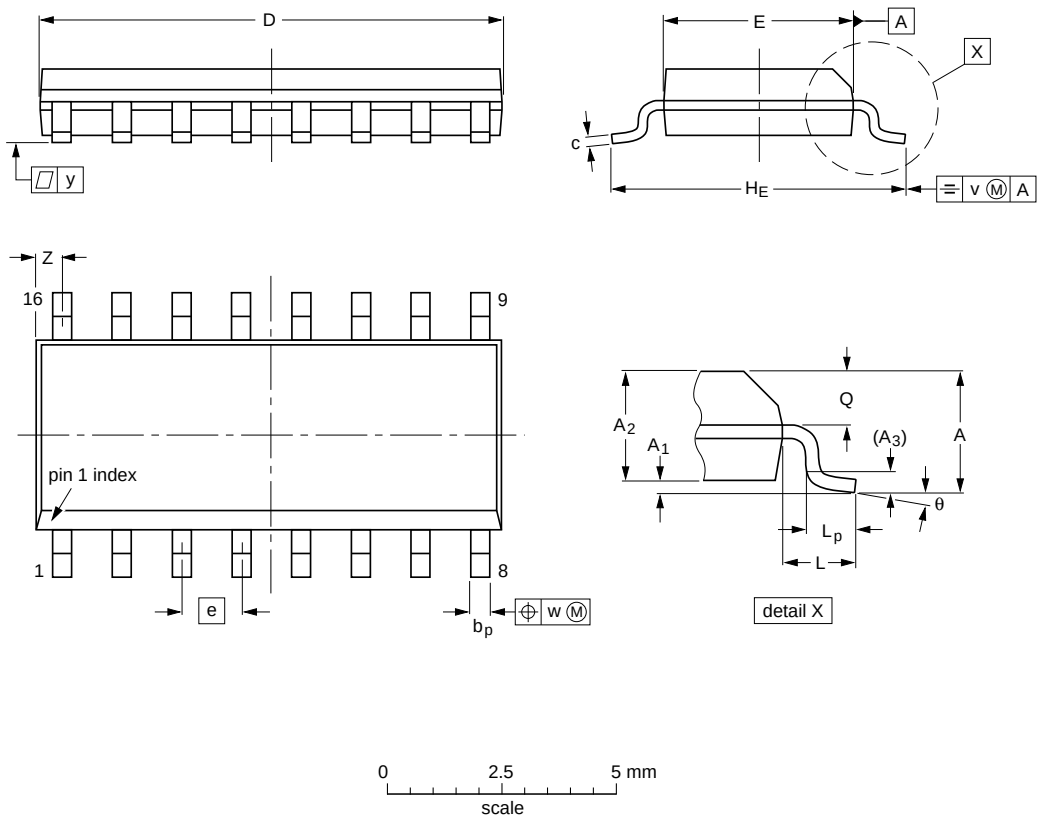
Fig 7. Load circuitry for switching times

Table 9. Test data

Supply voltage	Input		Load	
	V_I	t_r, t_f	C_L	R_L
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω

12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

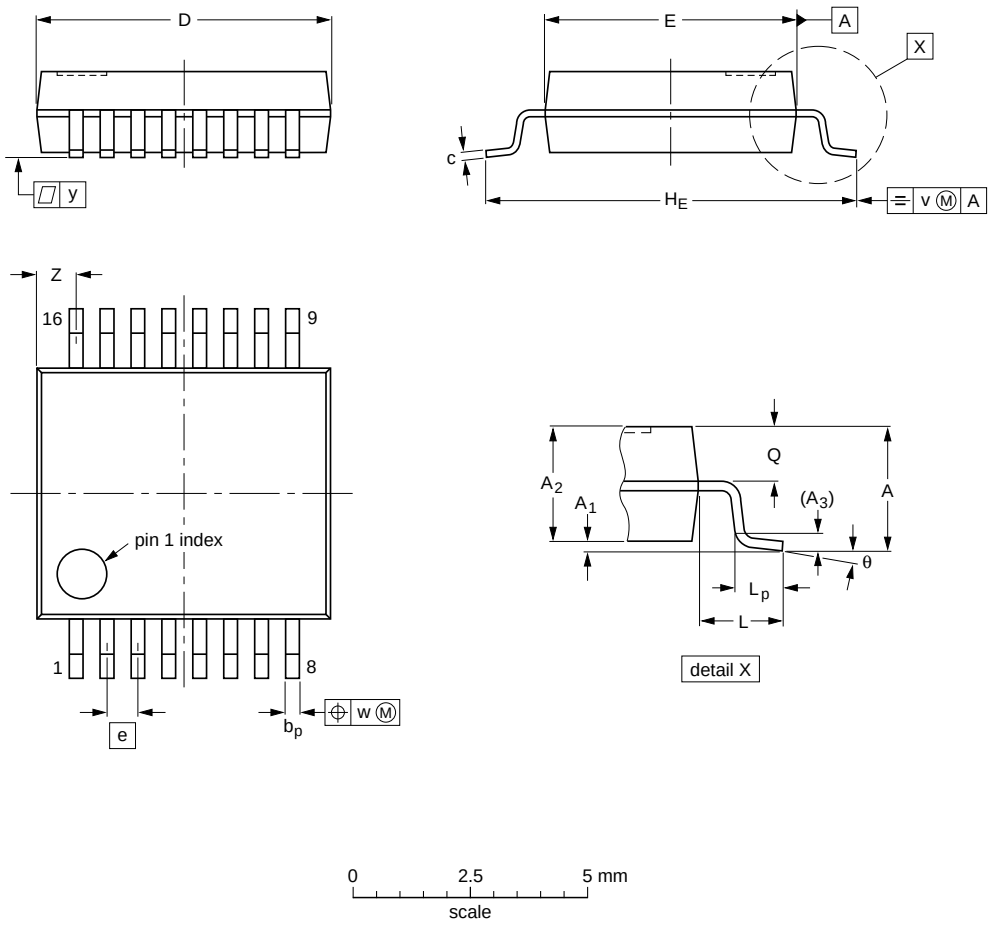
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig 8. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm **SOT338-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.00 0.55	8^o 0^o

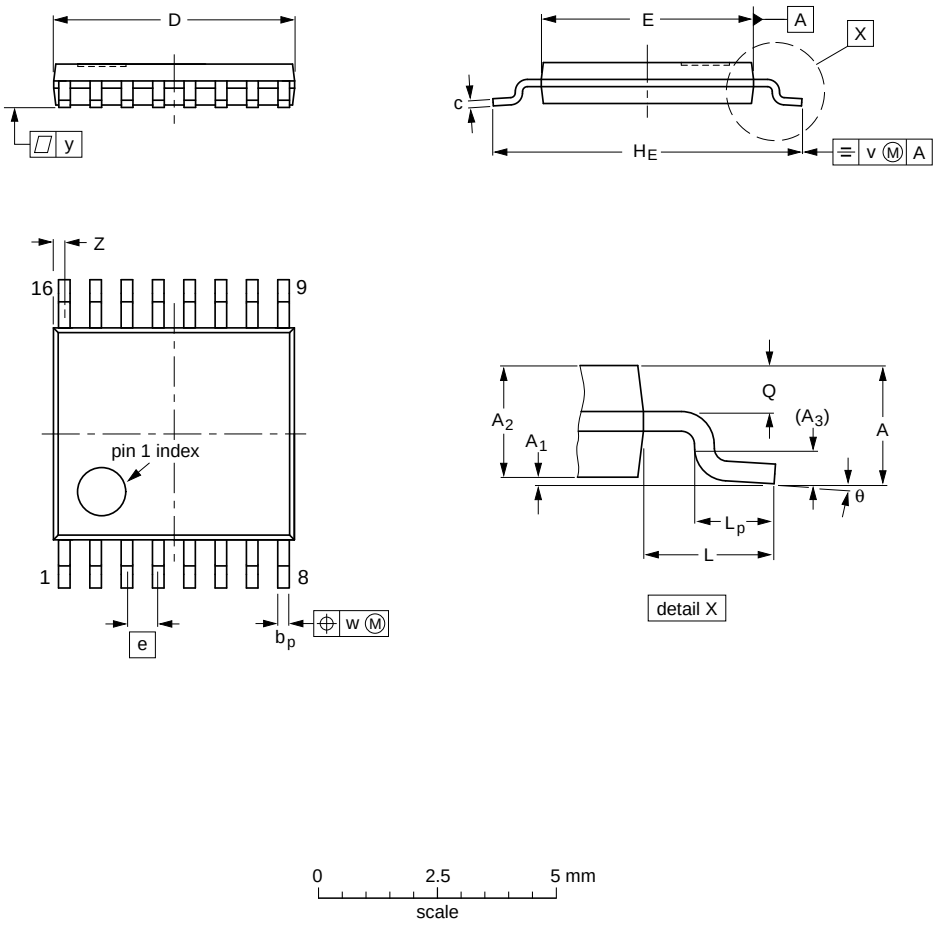
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT338-1		MO-150				~~99-12-27~~ 03-02-19

Fig 9. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig 10. Package outline SOT403-1 (TSSOP16)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC109 v.5	20121129	Product data sheet	-	74LVC109 v.4
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Table 4, Table 5, Table 6, Table 7 and Table 8: values added for lower voltage ranges.			
74LVC109 v.4	20040318	Product specification	-	74LVC109 v.3
74LVC109 v.3	19980428	Product specification	-	74LVC109 v.2
74LVC109 v.2	19970318	Product specification	-	74LVC109 v.1
74LVC109 v.1	-	-	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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17. Contents

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